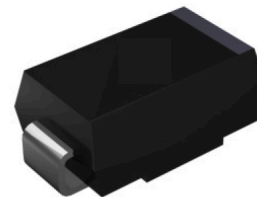


Features

- Low forward voltage drop
- High junction temperature
- Moisture sensitivity: level 1, per J-STD-020
- Plastic package has underwriters laboratory flammability classification 94V-0
- Add suffix 'E' for halogen-free
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT

Package: DO-214AB (SMC)

Applications

For use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	SK32 SK32E	SK33 SK33E	SK34 SK34E	SK35 SK35E	SK36 SK36E	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	30	40	50	60	V
Maximum RMS Voltage	V _{RMS}	14	21	28	35	42	V
Maximum DC Blocking Voltage	V _{DC}	20	30	40	50	60	V
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0					A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I _{FSM}	100					A
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150					°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	SK32 SK32E	SK33 SK33E	SK34 SK34E	SK35 SK35E	SK36 SK36E	Unit
Maximum Instantaneous Forward Voltage	I _F =3A	V _F	0.55			0.70		V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	0.20			0.15		mA
	T _A =125°C		10					
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	250					pF

Thermal Characteristics

Parameter	Symbol	SK32 SK32E	SK33 SK33E	SK34 SK34E	SK35 SK35E	SK36 SK36E	Unit
Typical Thermal Resistance ⁽¹⁾	R _{θJA}	65					°C/W
	R _{θJC}	25					
	R _{θJL}	15					

Note1: Thermal resistance from junction to lead, mounted on PCB with 8.0×8.0mm copper pads.

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

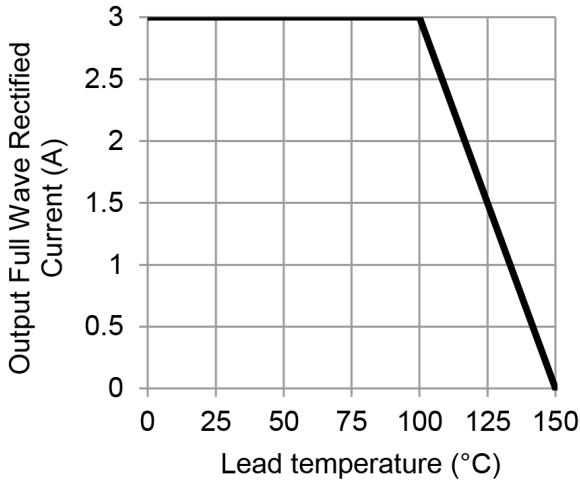


Figure 1. Forward Current Derating Curve

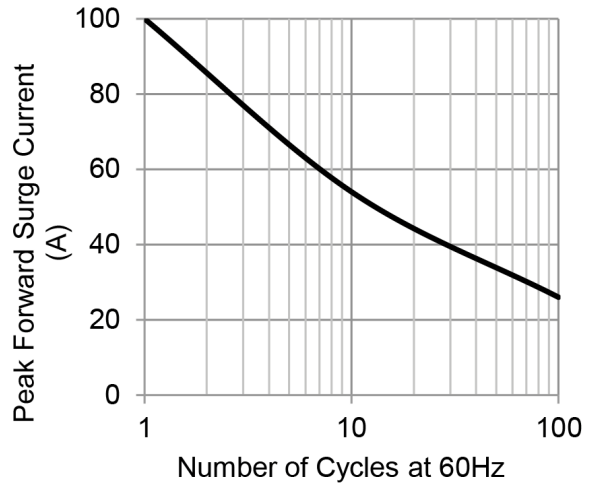


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

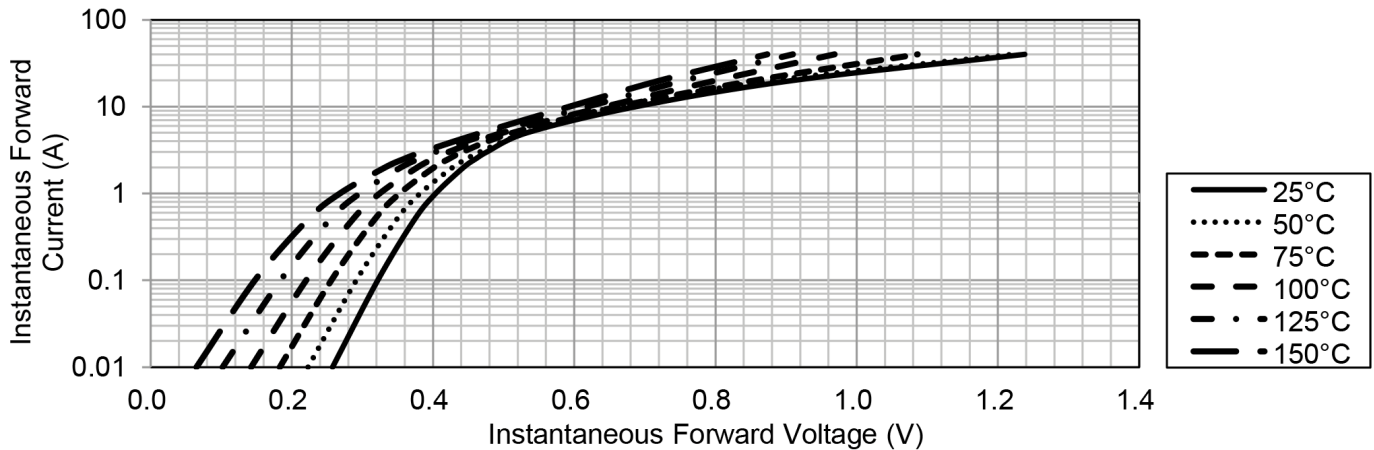


Figure 3. Typical Instantaneous Forward Characteristics (SK32 thru SK34)

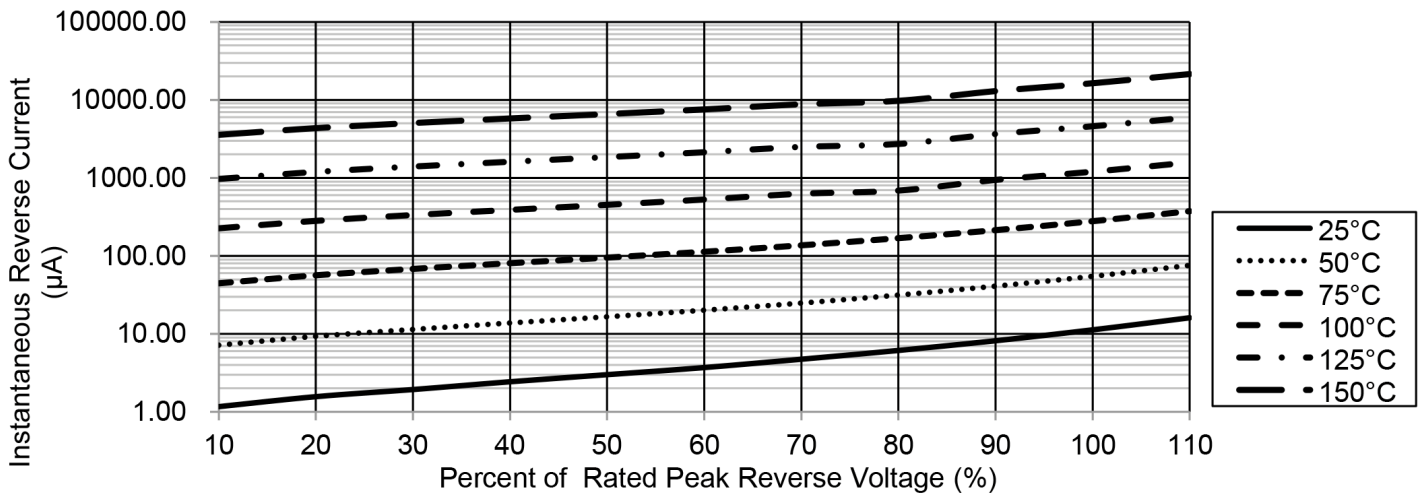


Figure 4. Typical Reverse Characteristics (SK32 thru SK34)

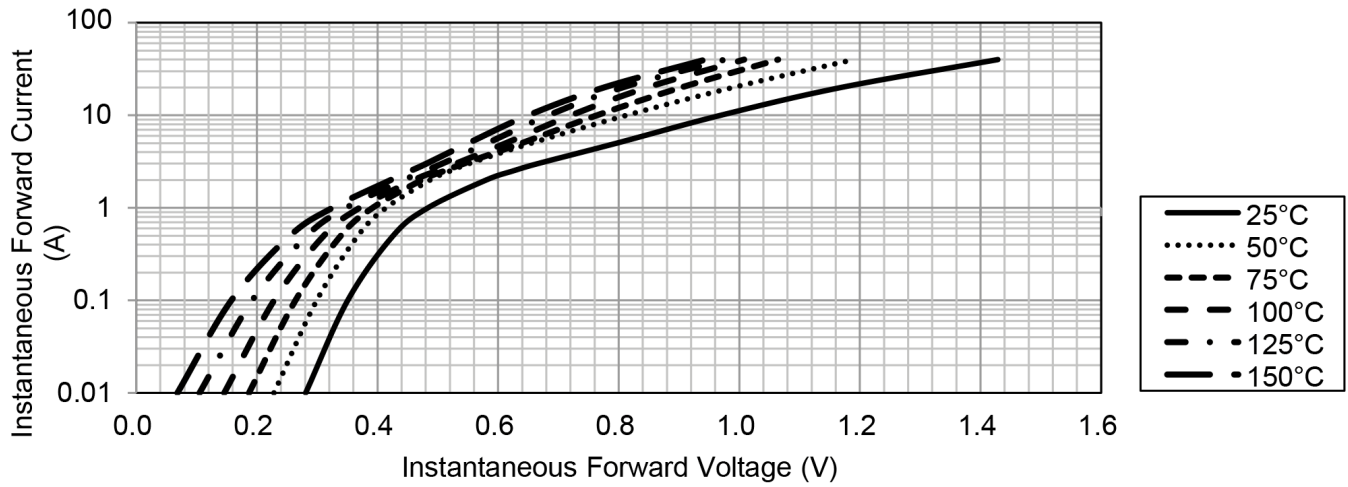


Figure 5. Typical Instantaneous Forward Characteristics (SK35 thru SK36)

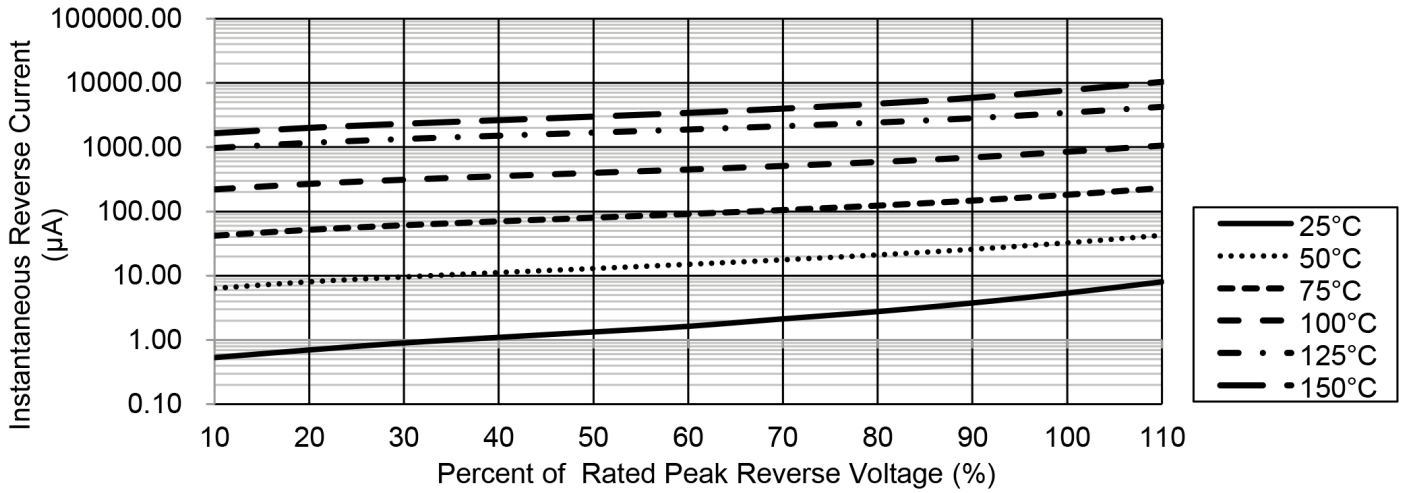
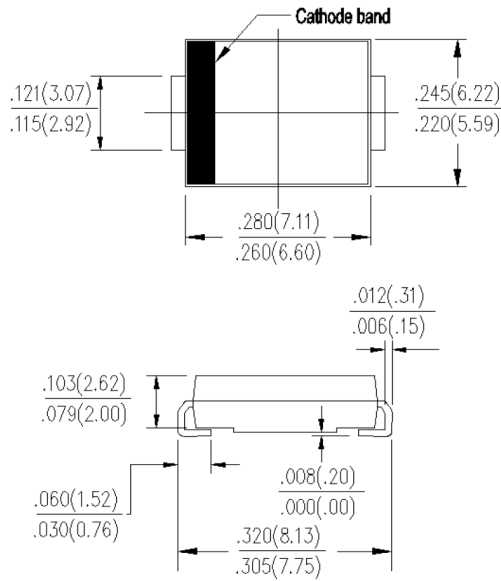


Figure 6. Typical Reverse Characteristics (SK35 thru SK36)

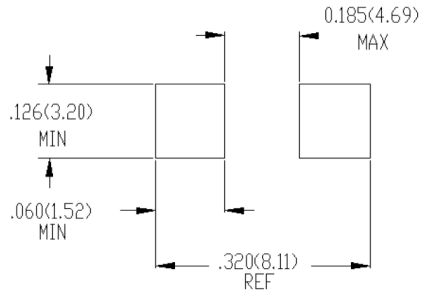
Package Outline Dimensions

DO-214AB (SMC)

in inches (millimeters)



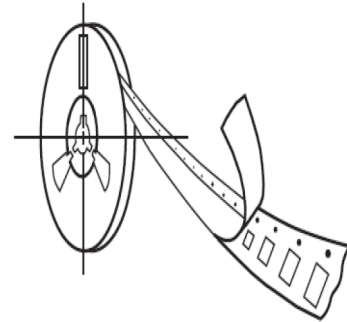
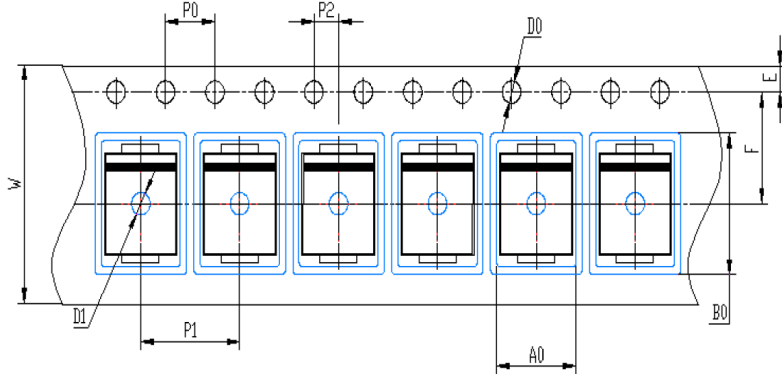
Mounting Pad Layout



Packing Information

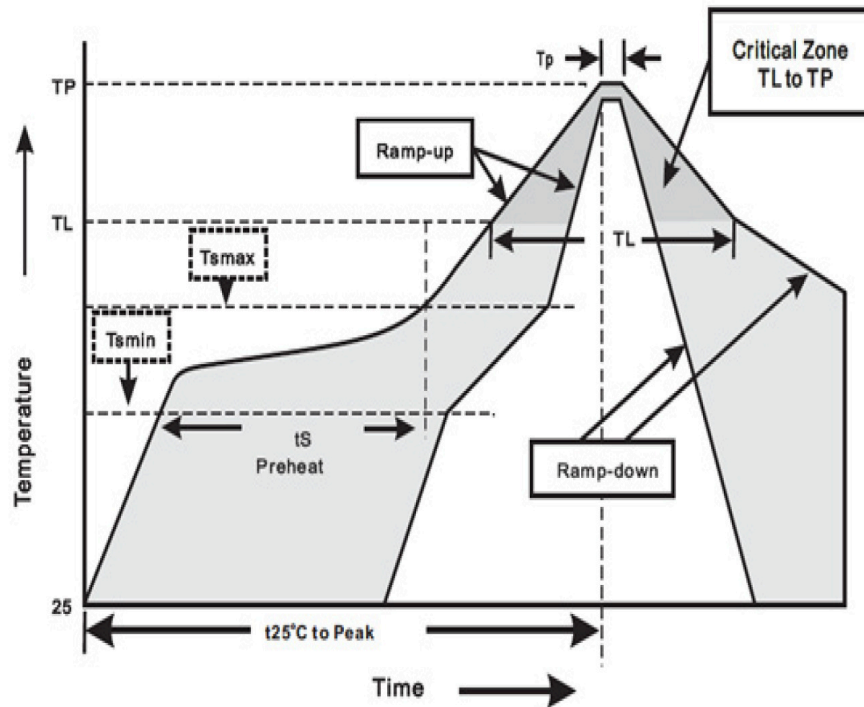
3000 pcs/Reel, 14 Reels/Box; 16mm Tape, 13" Reel

Tape & Reel Specification



Symbol	SMC(mm)
W	16±0.2
E	1.75±0.1
F	7.5±0.05
D0	1.5±0.1
D1	1.50 +0.1/-0
P0	4.0±0.1
P1	8.0±0.1
P2	2.0±0.05
A0	6.22±0.1
B0	8.31±0.1

Soldering Parameters



Reflow Soldering		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Pre Heat	- Temperature Min (Ts min)	100°C	150°C
	- Temperature Max (Ts max)	150°C	200°C
	- Time (min to max) (ts)	60 – 120 secs	60 – 180 secs
Average ramp up rate (Liquidus) Temp (TL) to peak		3°C/second max	3°C/second max
TS(max) to TL - Ramp-up Rate		3°C/second max	3°C/second max
Reflow	- Temperature (TL) (Liquidus)	183°C	217°C
	- Time (min to max) (ts)	60 – 150 seconds	60 – 150 seconds
Peak Temperature (TP)		240+0/-5 °C	240+0/-5°C
Time within 5°C of actual peak Temperature (tp)		10 –30 seconds	20 – 40 seconds
Ramp-down Rate		6°C/second max	6°C/second max
Time 25°C to peak Temperature (TP)		6 minutes max	8 minutes max
Do not exceed		260°C	260°C

Wave Soldering	
Peak Temperature	260+0/-5°C
Dipping Time	10 seconds
Soldering	1 time